EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	584	packag$3 same (foil sheet) near3 (metal metallic) with (etch$3 etching)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 17:12
L2	192	1 and packag$3 with ("IC" die chip) near3 (pad pading)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 17:13
L3	209	1 and packag$3 with ("IC" die chip) near3 (pad pad$3 pading)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 17:13
L4	31	3 and (foil sheet) near3 (metal metallic) with (substrate workpiece wafer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 17:15
L5	16976	438/108,111-112,123. ccls. 257/666-676, E32.046,E23.031, E21.001.CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 18:27
L6	632	5 and packag$3 same (foil sheet) near3 (metal metallic)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 18:27
L7	31	6 AND packag$3 with ("IC" die chip) near3 (pad pading) with (contact near3 (lead wire wiring))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 18:28

L8	295	6 AND packag$3 with ("IC" die chip) near3 (pad pading)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 18:28
S61	1	10/598390	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 10:07
S63	372	("20020027010" | "20030034697" | "20040110319" | "20040017668" | "4963414" | "6143981" | "6294100" | "6342730" | "6498099")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 10:10
S64	18	("20020027010" | "20030034697" | "20040110319" | "20040017668" | "4963414" | "6143981" | "6294100" | "6342730" | "6498099").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 11:36
S65	20418	packag$3 with ("IC" die chip) near3 (pad pading)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 12:21
S66	536	packag$3 with ("IC" die chip) near3 (pad pading) with (contact near3 (lead wire wiring))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 12:23
S67	51	S66 and packag$3 same (foil sheet) near3 (metal metallic)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 12:25

1/7/2010 6:29:08 PM
C:\ Documents and Settings\ dle5\ My Documents\ EAST\ Workspaces\ 8390a.wsp